Updated junction-to-top characterization parameter from 3.1°CW to 6.1°CW	PCN Number:	20190	107002	.0 PCN	N Date:	anua	ry 08,	2019
Change Type: Assembly Site Assembly Process Data Sheet Assembly Process Mafer Bump Material Assembly Mechanical Specification Test Site Mafer Bump Process Mafer Bump Process Mafer Bump Process Mafer Fab Site Mafer Fab Site Mafer Fab Materials Mafer Fab Materials Mafer Fab Materials Wafer Fab Process Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS TMP102-Q1 SBOST020 - OCTOBER 2014 - REVISED DECEMBER 2018 Changes from Revision C (December 2015) to Revision D Changed the supply voltage maximum value from: 3.6 V to: 4 V. 4 Updated junction-to-ambient thermal resistance from 200°CW to 210.3°CW. 5 Updated junction-to-bard thermal resistance from 73.7°CW to 105.0°CW. 5 Updated junction-to-load themal resistance from 3.1°CW to 87.5°CW. 5 Updated junction-to-load themal resistance from 3.1°CW to 6.1°CW. 5 Updated junction-to-board characterization parameter from 3.1°CW to 6.1°CW. 5 Updated junction-to-board characterization parameter from 3.1°CW to 6.1°CW. 5 Updated junction-to-board characterization parameter from 3.1°CW to 87.0°CW. 5 Updated junction-to-board characterization parameter from 3.1°CW to 6.1°CW. 5 Updated junction-to-board characterization parameter from 3.1°CW to 6.1°CW. 5 Updated junction-to-board characterization parameter from 3.1°CW to 6.1°CW. 5 Updated junction-to-board characterization parameter from 3.1°CW to 6.1°CW. 5 Updated junction-to-board characterization parameter from 3.1°CW to 6.1°CW. 5 Updated junction-to-board characterization parameter from 3.1°CW to 6.1°CW. 5 Updated junction-to-board characterization parameter from 3.1°CW to 6.1°CW. 5 Updated	Title: Datasheet for TMP102-Q1							
Assembly Process Data Sheet Wafer Bump Site Wafer Bump Process Data Sheet Wafer Bump Materials Assembly Materials Part number change Wafer Bump Process Wafer Fab Site Wafer Fab Site Wafer Fab Site Wafer Fab Materials Wafer Fab Process Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS INSTRUMENTS TMP102-01 SEOSTOZD - OCTOBER 2014-REVISED DECEMBER 2018 Changes from Revision C (December 2015) to Revision D Page Changed the supply voltage maximum value from: 3.6 V to: 4 V. 4 Updated junction-to-ambient thermal resistance from 200°CM to 210.3°CM Updated junction-to-board thermal resistance from 73.7°CM to 105.0°CM Updated junction-to-board thermal resistance from 34.4°CM to 87.5°CM Updated junction-to-board characterization parameter from 31.7°CM to 61.7°CM Updated junction-to-pop characterization parameter from 34.2°CM to 87.0°CM Added the Receiving Notification of Documentation Updates section Device Family Change From: Change To: TMP102-Q1 The datasheet number will be changing. Device Family Change From: Change To: TMP102-Q1 These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/TMP102-Q1 Reason for Change: To accurately reflect device characteristics. Anticipated impact. This is a specification change announcement only. There are no changes to the actual device. Changes to product identification resulting from this PCN: None.	Customer Contact:	PCN Ma	nager			Dep	ot:	Quality Services
Assembly Process Assembly Materials Part number change Wafer Bump Material	Change Type:							
Assembly Materials	Assembly Site			Design			Wafer	· Bump Site
Mechanical Specification Test Site Wafer Fab Site Wafer Fab Materials Wafer Fab Materials Wafer Fab Materials Wafer Fab Process Wa	Assembly Process			Data Sheet			Wafer	Bump Material
Packing/Shipping/Labeling Test Process Wafer Fab Materials Wafer Fab Process							Wafer	Bump Process
Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS TMP102-Q1 SECONTOCO CTOCO				Test Site			Wafer	Fab Site
Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS TOPIO2-Q1 SEOSTO2D - OCTOBER 2014 - REVISED DECEMBER 2018 Changes from Revision C (December 2015) to Revision D Page Changed the supply voltage maximum value from: 3.6 V to: 4 V	Packing/Shipping/	Labeling		Test Process			Wafer	Fab Materials
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TIEXAS TMP102-Q1 TEXAS TMP102-Q1 SEOSTOZO - OCTOBER 2014 - REVISED DECEMBER 2018 Changes from Revision C (December 2015) to Revision D Page Changed the supply voltage maximum value from: 3.6 ∨ to: 4 ∨							Wafer	Fab Process
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS	Notification Details							
The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS INSTRUMENTS TMP102-Q1 SB05702D - OCTOBER 2014 - REVISED DECEMBER 2018 Changes from Revision C (December 2015) to Revision D Page Changed the supply voltage maximum value from: 3.6 V to: 4 V Updated junction-to-ambient thermal resistance from 200°CM to 210.3°CM Updated junction-to-case (top) thermal resistance from 73.7°CM to 105.0°CM Updated junction-to-board thermal resistance from 34.4°CM to 87.5°CM Updated junction-to-top characterization parameter from 31.7°CM to 6.1°CM SUpdated junction-to-top characterization parameter from 31.2°CM to 87.0°CM SUpdated junction-to-board characterization parameter from 34.2°CM to 87.0°CM SUpdated junction-to-board characterization parameter from 31.2°CM to 87.0°CM SUpdated junction-to-board characterization parameter from 34.2°CM to 87.0°CM SUPDATEDATE SUPDATE SUPDATEDATE SUPDATE	Description of Chang	je:						
The following change history provides further details. TMP102-Q1 SECTION STRUMENTS TMP102-Q1 SECTION SECTION OF COLORER 2014 - REVISED DECEMBER 2018 Changes from Revision C (December 2015) to Revision D Page Changed the supply voltage maximum value from: 3.6 V to: 4 V Updated junction-to-ambient thermal resistance from 200°CW to 210.3°CW 5 Updated junction-to-case (top) thermal resistance from 73.7°CW to 105.0°CW 5 Updated junction-to-board thermal resistance from 34.4°CW to 87.5°CW 5 Updated junction-to-board thermal resistance from 34.4°CW to 87.5°CW 5 Updated junction-to-board characterization parameter from 31.°CW to 6.1°CW 5 Updated junction-to-board characterization parameter from 34.2°CW to 87.0°CW 5 Added the Receiving Notification of Documentation Updates section 24 The datasheet number will be changing. Device Family Change From: Change To: TMP102-Q1 SBOS702C SBOS702D These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/TMP102-Q1 Reason for Change: To accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device. Changes to product identification resulting from this PCN: None. Product Affected:		•		•		•	tificatio	on.
TEXAS INSTRUMENTS Changes from Revision C (December 2015) to Revision D Page Changed the supply voltage maximum value from: 3.6 V to: 4 V Updated junction-to-ambient thermal resistance from 200°C/W to 210.3°C/W Updated junction-to-board thermal resistance from 73.7°C/W to 105.0°C/W Updated junction-to-board thermal resistance from 73.7°C/W to 105.0°C/W Updated junction-to-board thermal resistance from 34.4°C/W to 87.5°C/W Updated junction-to-board characterization parameter from 31.0°C/W SBOS702/W SBOS702/C SBOS702D These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/TMP102-Q1 Reason for Change: To accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device. Changes to product identification resulting from this PCN: None. Product Affected:					ized below.			
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Changed the supply voltage maximum value from: 3.6 V to: 4 V					3803	7020-	OCTOBER	2014-REVISED DECEMBER 2016
Updated junction-to-ambient thermal resistance from 200°CW to 210.3°CW	Changes from Revision C (December	2015) to	Revision D				Page
Updated junction-to-ambient thermal resistance from 200°CW to 210.3°CW	Changed the supply voltage maximum value from: 3.6 V to: 4 V							
Updated junction-to-case (top) thermal resistance from 73.7°C/W to 105.0°C/W								
Updated junction-to-board thermal resistance from 34.4°CW to 87.5°CW								
Updated junction-to-top characterization parameter from 3.1°C/W to 6.1°C/W								
Updated junction-to-board characterization parameter from 34.2°C/W to 87.0°C/W								
Added the Receiving Notification of Documentation Updates section								
The datasheet number will be changing. Device Family TMP102-Q1 TMP102-Q1 SBOS702C SBOS702D These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/TMP102-Q1 Reason for Change: To accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device. Changes to product identification resulting from this PCN: None. Product Affected:								
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These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/TMP102-Q1 Reason for Change: To accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device. Changes to product identification resulting from this PCN: None. Product Affected:	TMP102-Q1	TMP102-O1			SBOS702C			SBOS702D
Reason for Change: To accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device. Changes to product identification resulting from this PCN: None. Product Affected:								
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Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device. Changes to product identification resulting from this PCN: None. Product Affected:	Reason for Change:							
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None. Product Affected:								
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TMP102AODRLRO1	Product Affected:							
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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